



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPD040N03L G	<b>Issued</b>	24. June 2021
<b>MA#</b>	MA000655936		
<b>Package</b>	PG-TO252-3-311	<b>Weight*</b>	318.32 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.734	0.54	0.54	5448	5448
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		135	
	non noble metal	iron	7439-89-6	0.143	0.04		450	
	non noble metal	copper	7440-50-8	143.098	44.98	45.03	449548	450133
wire	non noble metal	aluminium	7429-90-5	4.472	1.40	1.40	14050	14050
encapsulation	organic material	carbon black	1333-86-4	0.317	0.10		995	
	plastics	epoxy resin	-	19.124	6.01		60080	
	inorganic material	silicondioxide	60676-86-0	124.567	39.13	45.24	391333	452408
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11749	11749
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	272	273
solder	non noble metal	tin	7440-31-5	0.036	0.01		112	
	noble metal	silver	7440-22-4	0.045	0.01		140	
	non noble metal	lead	7439-92-1	1.707	0.54	0.56	5362	5614
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.02	6.03	60247	60325
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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